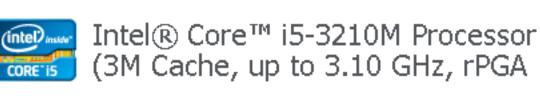
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Specifications | Essentials Performance Memory Specifications Graphics Specifications **Expansion Options** Package Specifications Advanced Technologies Intel® Data Protection Technology Intel® Platform Protection Technology Compatible Products

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Specifications Essentials Status Launched Launch Date Q2'12 Processor Number i5-3210M Intel® Smart Cache 3 МВ 5 GT/s DMI 64-bit Instruction Set AVX. Instruction Set Extensions Q No Embedded Options Available Lithography: 22 nm TRAY: \$225.00 Recommended Customer Price Conflict Free Datasheet Link Performance

2

2.5 GHz

3.1 GHz

35 W

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SROMZ 919697; PCN | MDDS

PCN/MDDS Information

 Memory Specifications Max Memory Size (dependent on memory type) 32 GB DDR3/L/-RS 1333/1600 Memory Types Max # of Memory Channels Max Memory Bandwidth 25.6 GB/s Q No ECC Memory Supported * Graphics Specifications Intel® HD Graphics 4000

Processor Graphics # Graphics Base Frequency 650 MHz Graphics Max Dynamic Frequency 1.1 GHz eDP/DP/HDMI/SDVO/CRT Graphics Output Yes Intel® Quick Sync Video Intel® InTru™ 3D Technology Intel® Insider™ Q Intel® Wireless Display Yes Intel® Flexible Display Interface (Intel® FDI) Intel® Clear Video HD Technology # of Displays Supported * 3 Device ID: 166 Expansion Options

 Package Specifications Max CPU Configuration 1 105 C TJUNCTION Package Size 37.5 x 37.5mm (rPGA988B) Graphics and IMC Lithography 22 nm Sockets Supported FCPGA988

3.0

1x16, 2x8, 1x8 2x4

See MDDS

 Advanced Technologies Intel® Turbo Boost Technology * 2.0 Q No Intel® vPro Technology * Q Intel® Hyper-Threading Technology * Yes Intel® Virtualization Technology (VT-x) * Intel® Virtualization Technology for Directed I/O No Q (VT-d) # Intel® VT-x with Extended Page Tables (EPT) * Q Q Intel® 64 * Yes Intel® My WiFi Technology 4G WiMAX Wireless Technology Idle States Q Enhanced Intel SpeedStep® Technology Yes Q No Intel® Demand Based Switching Thermal Monitoring Technologies Intel® Fast Memory Access Intel® Flex Memory Access Intel® Identity Protection Technology *

 Intel® Data Protection Technology Q AES New Instructions Yes Secure Key Intel® Platform Protection Technology Q No Trusted Execution Technology * Execute Disable Bit # Anti-Theft Technology

compatibility of the products listed. Please contact system vendor for more information on specific products or systems. "Intel classifications" consist of Export Control Classification Numbers (ECCN) and Harmonized Tariff Schedule (HTS) numbers. Any use made of Intel classifications are without recourse to Intel and shall not be construed as a representation or warranty regarding the proper ECCN or HTS. Your company may be the exporter of record, and as such, your company is responsible for determining the correct classification of any item at the time of export.

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Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

/www/us/en/processors/processor-numbers.html for details.

Refer to Datasheet for formal definitions of product properties and features.

This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard,

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration. "Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader

sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers. See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which

processors support Intel® HT Technology. Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology, See www.intel.com/technology/turboboost/ for more information.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers, typically represent 1,000-unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

Product Specifications (ARK)

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

For benchmarking data see http://www.intel.com/performance. Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS. Send us your feedback!

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